

FIG.1

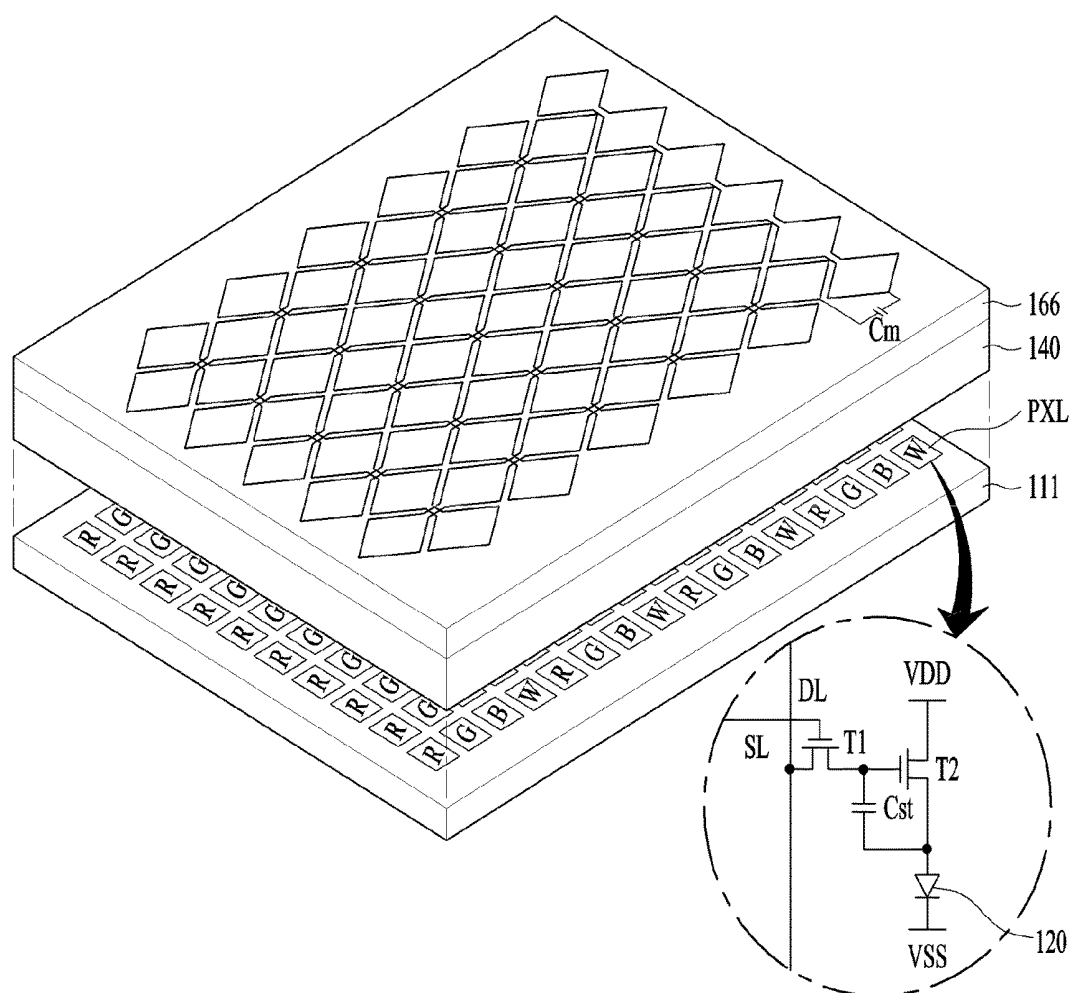


FIG.2

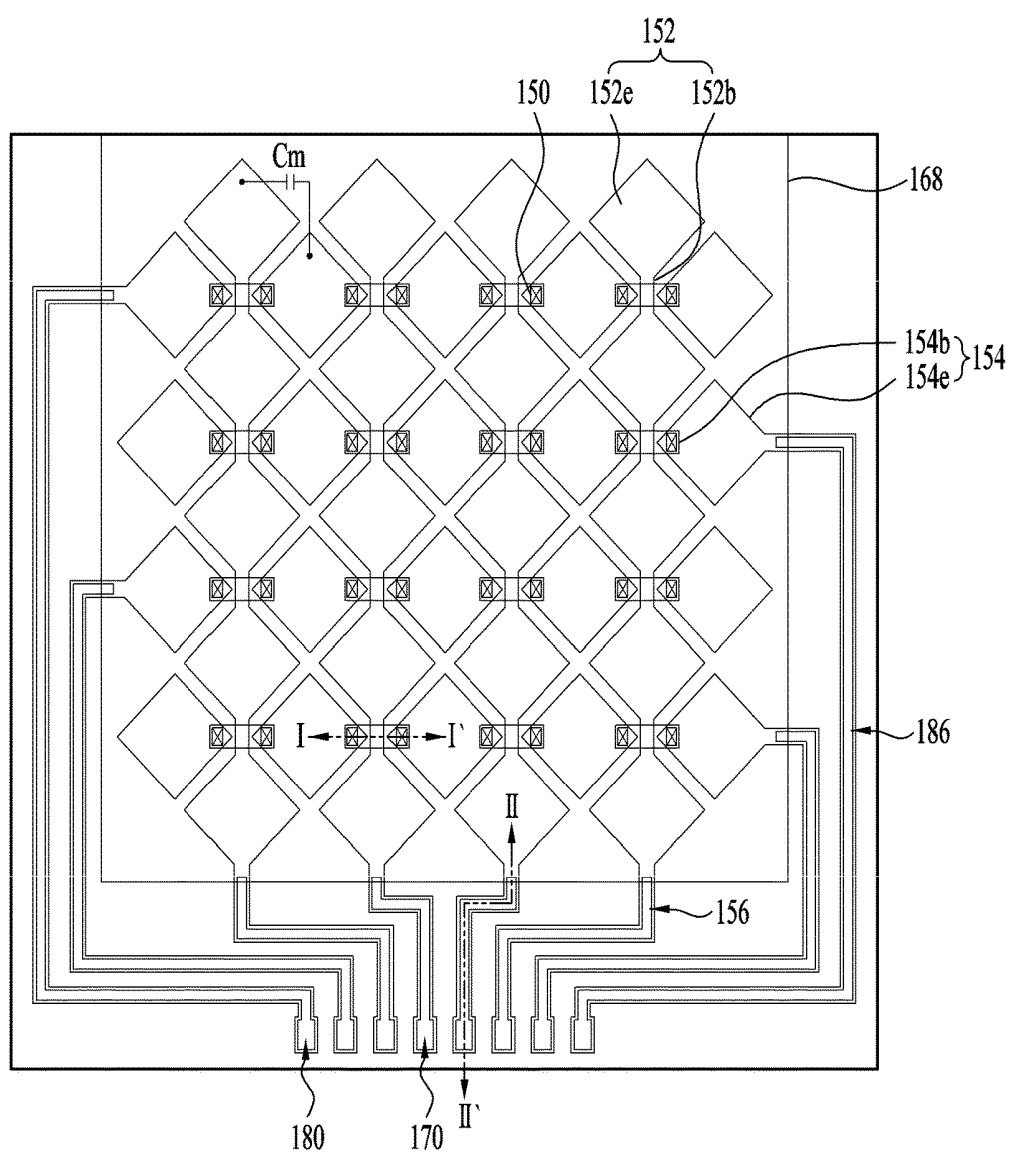


FIG.3

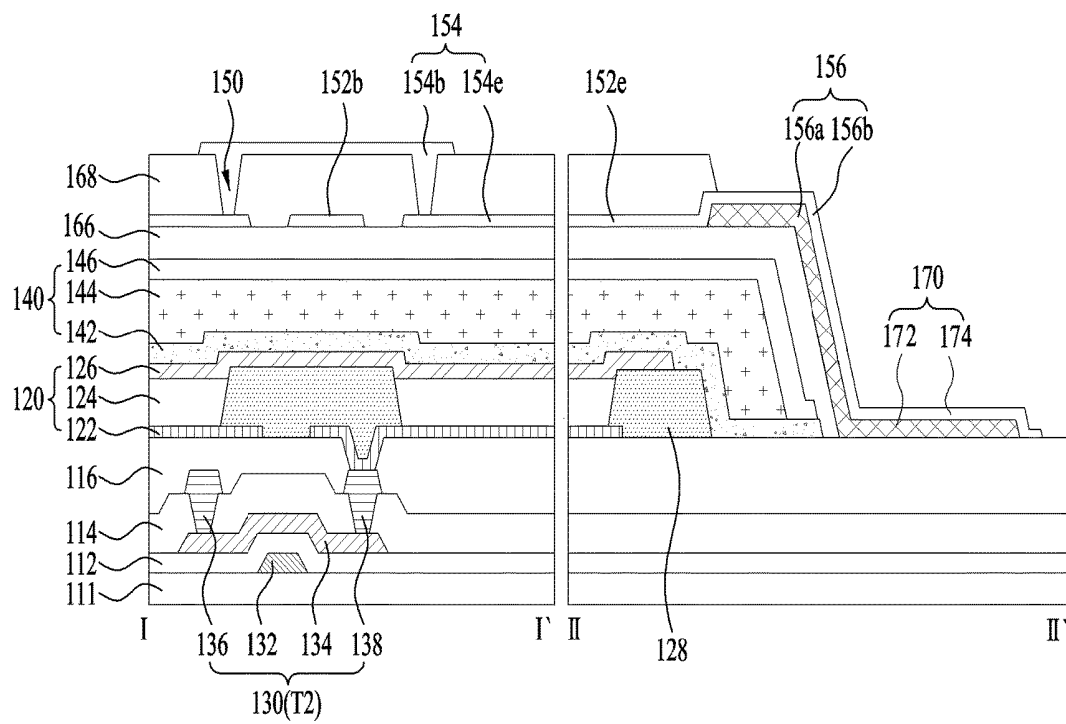


FIG.4A

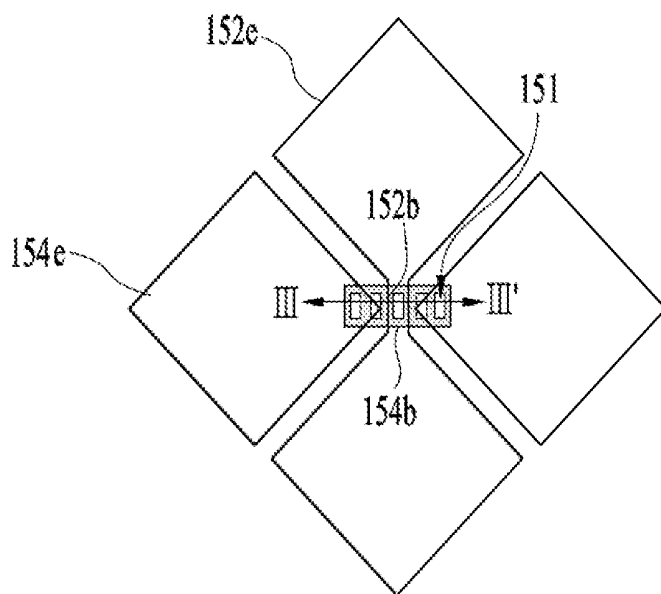


FIG.4B

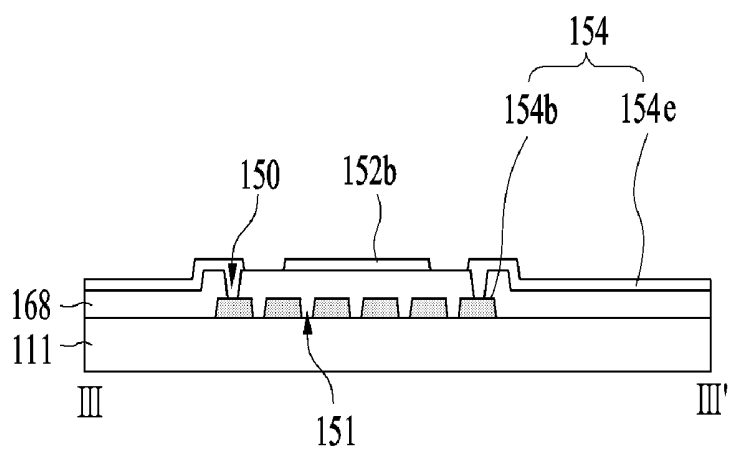


FIG. 5

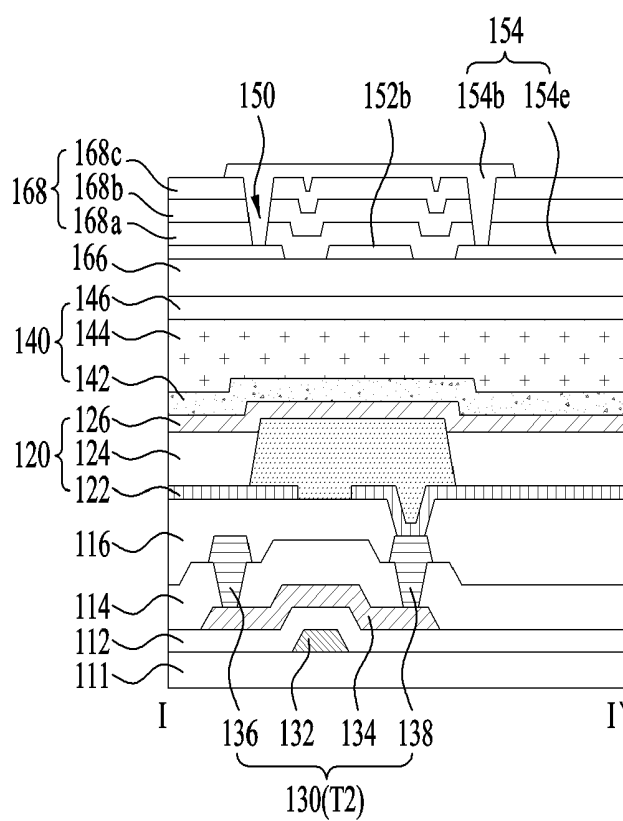


FIG.6A

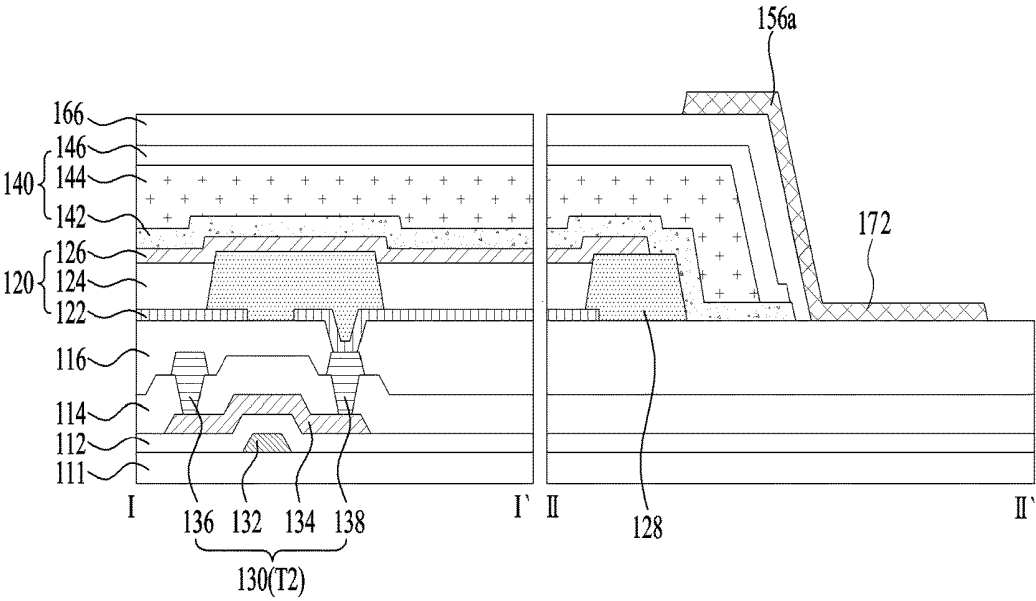


FIG.6B

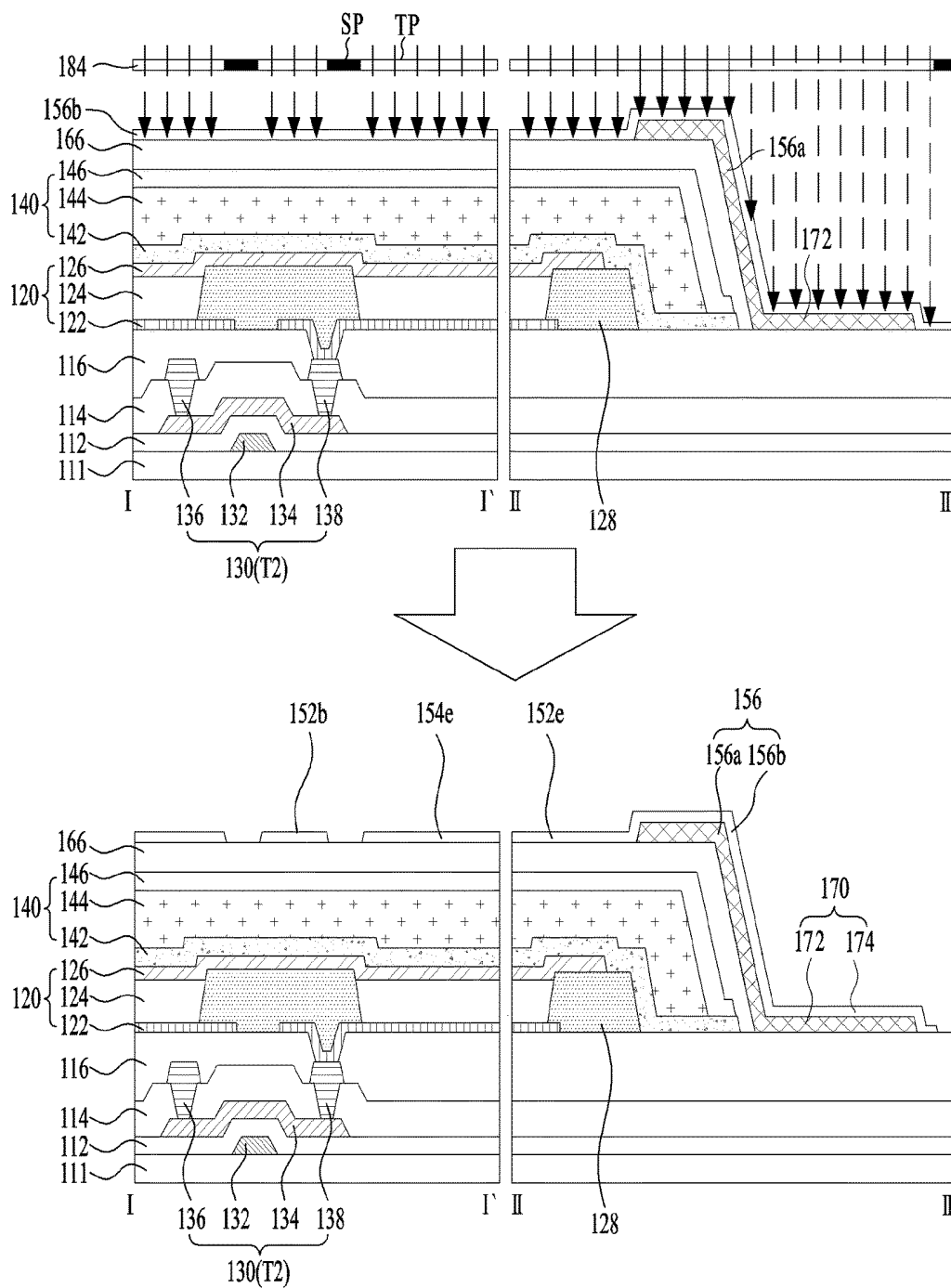


FIG.6C

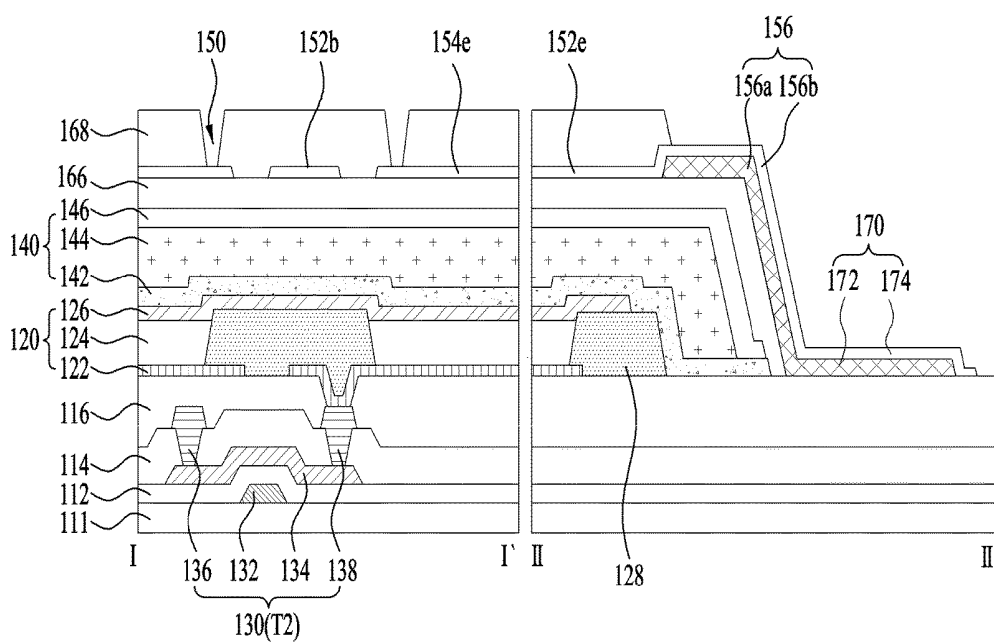


FIG.6D

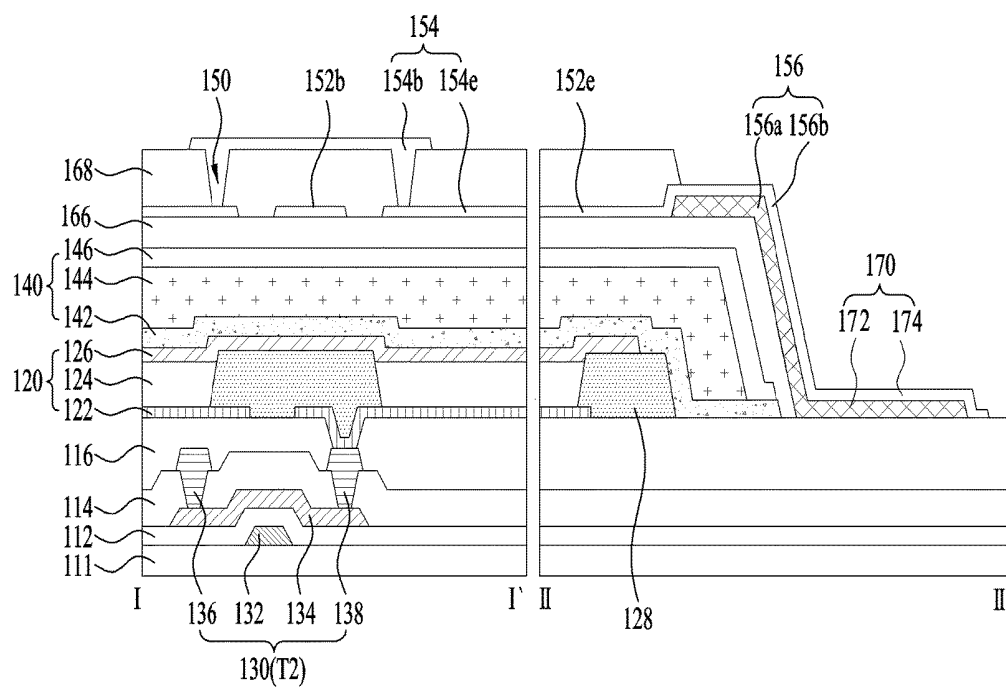


FIG. 7

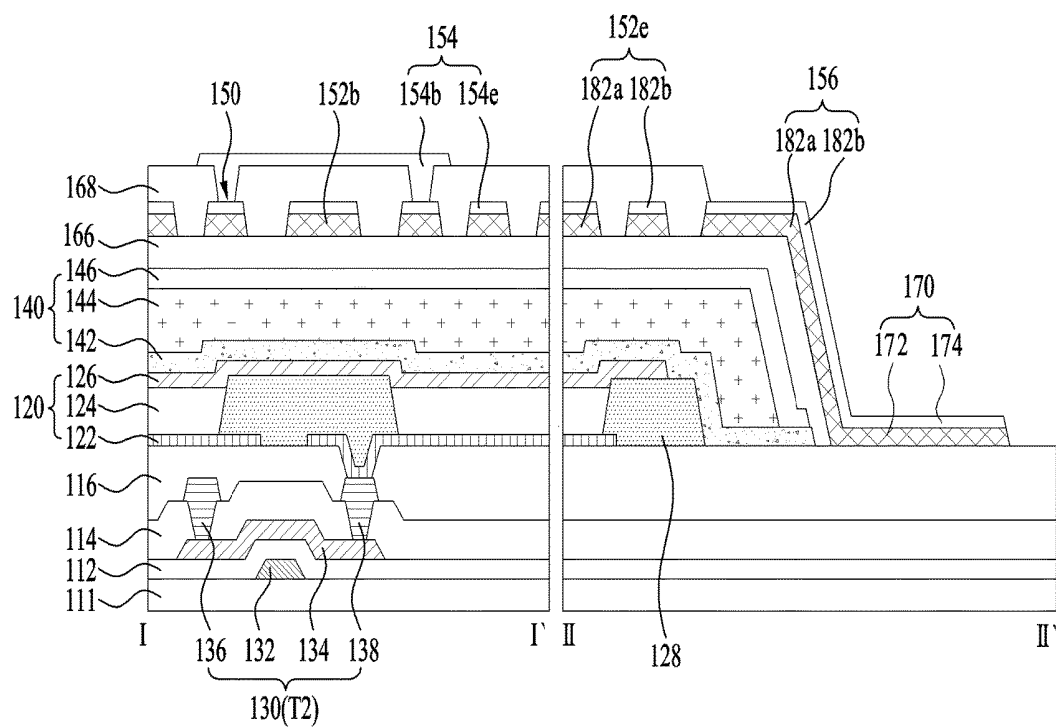


FIG.8

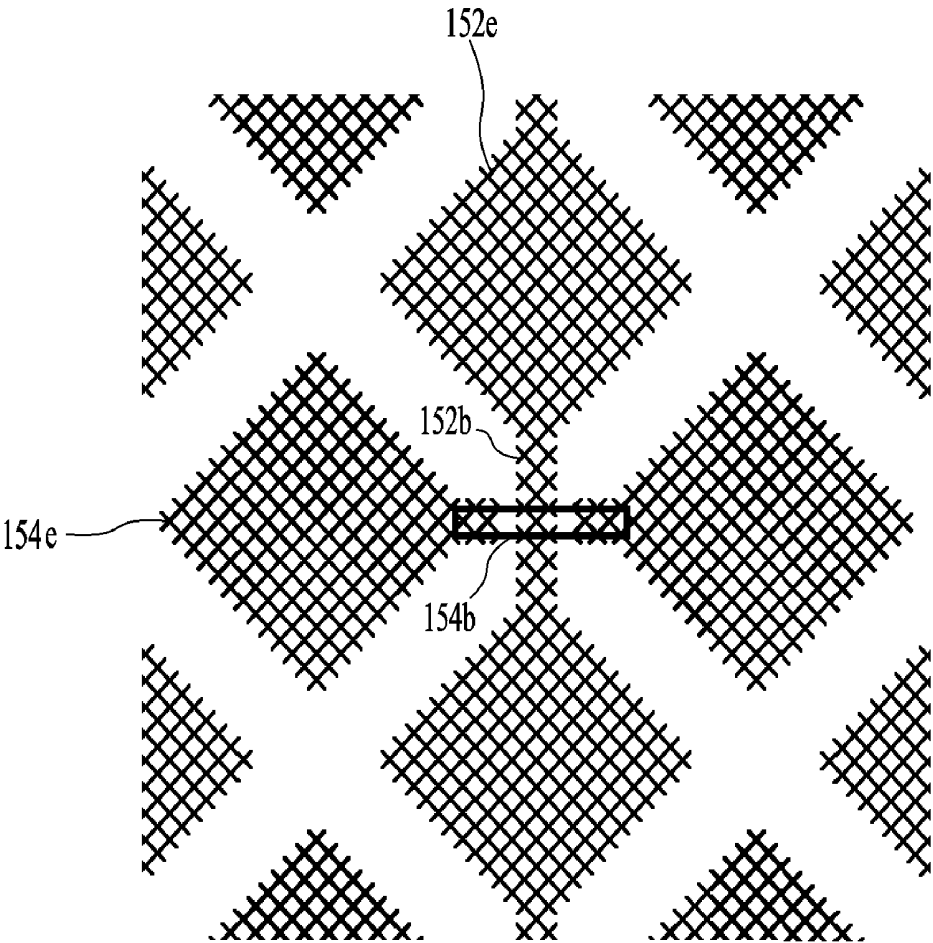


FIG.9A

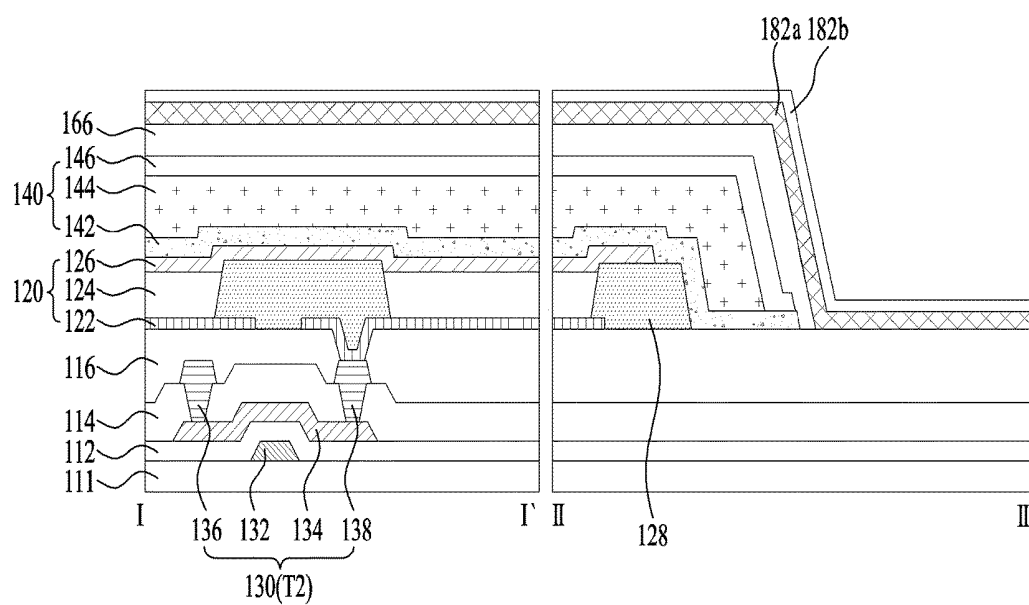


FIG.9B

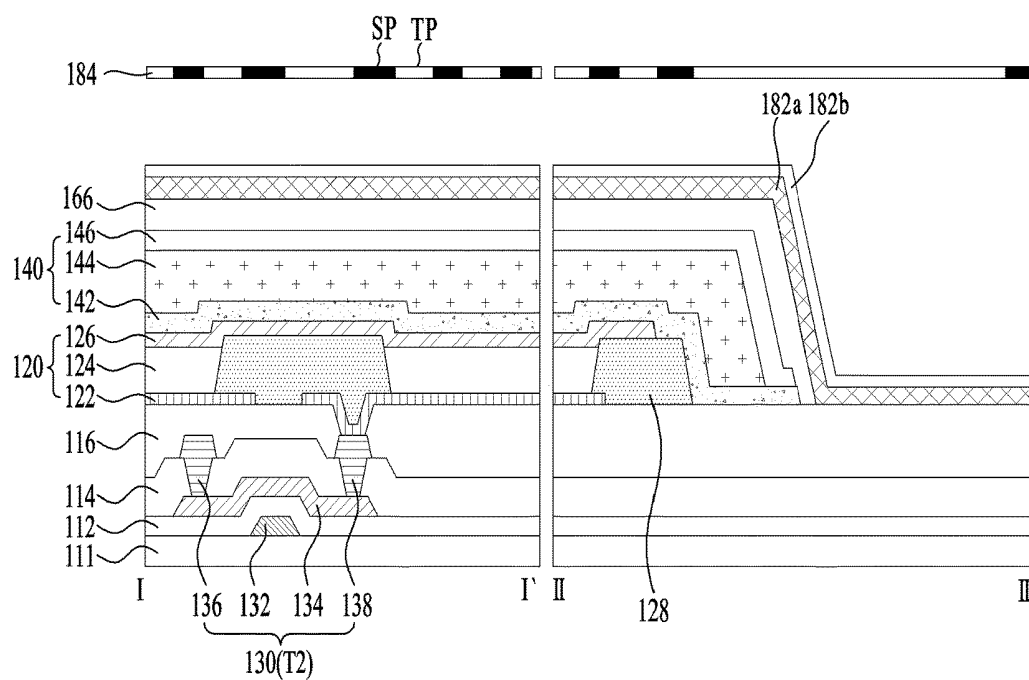


FIG.9C

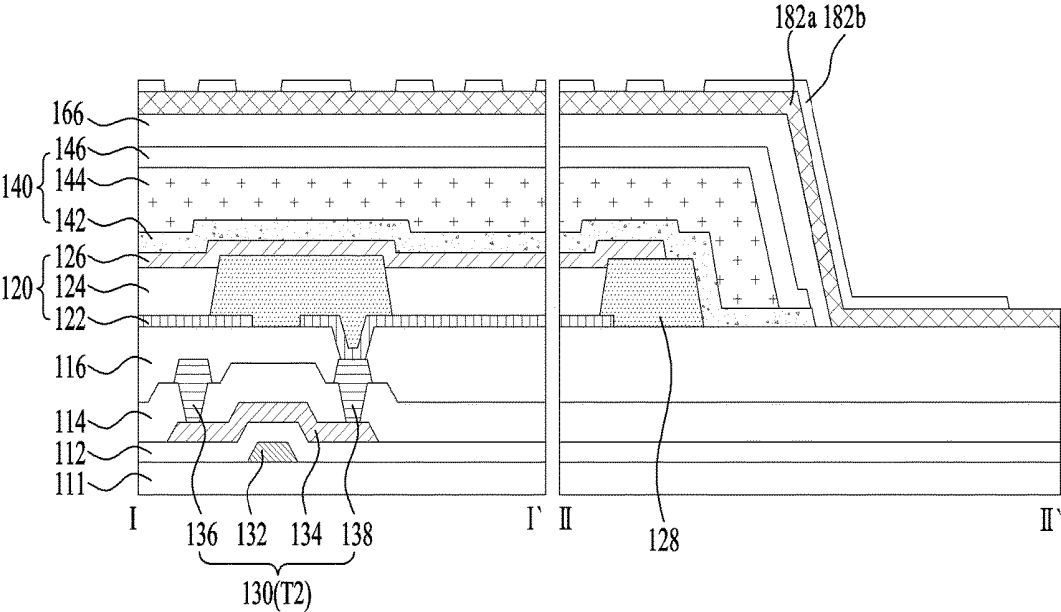


FIG.9D

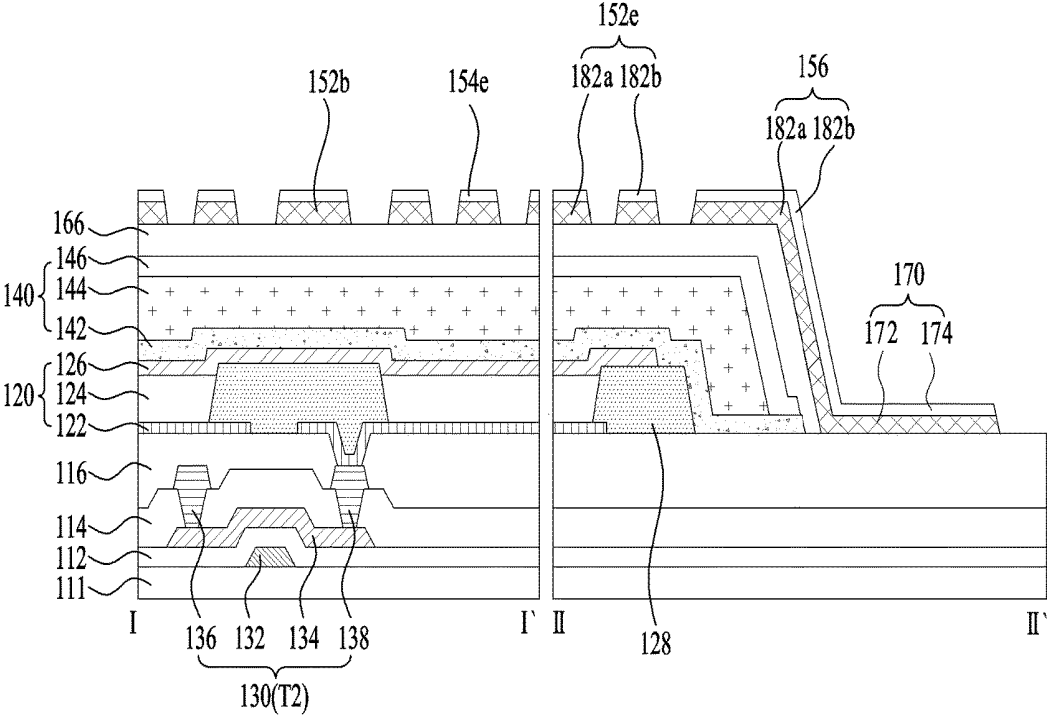


FIG.9E

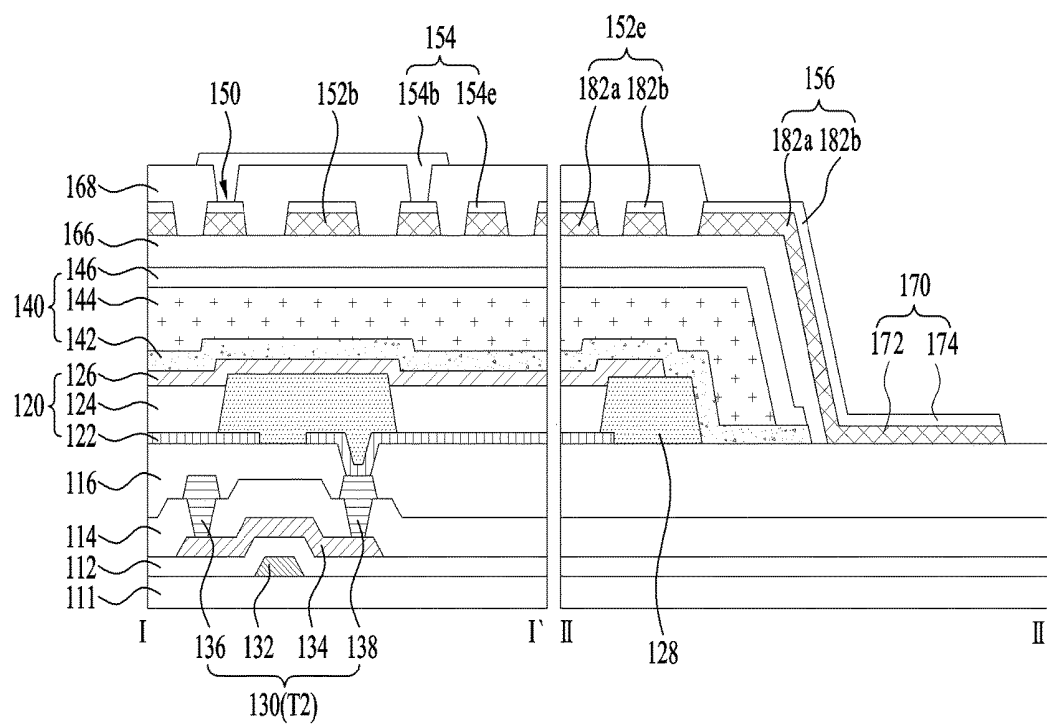


FIG.10

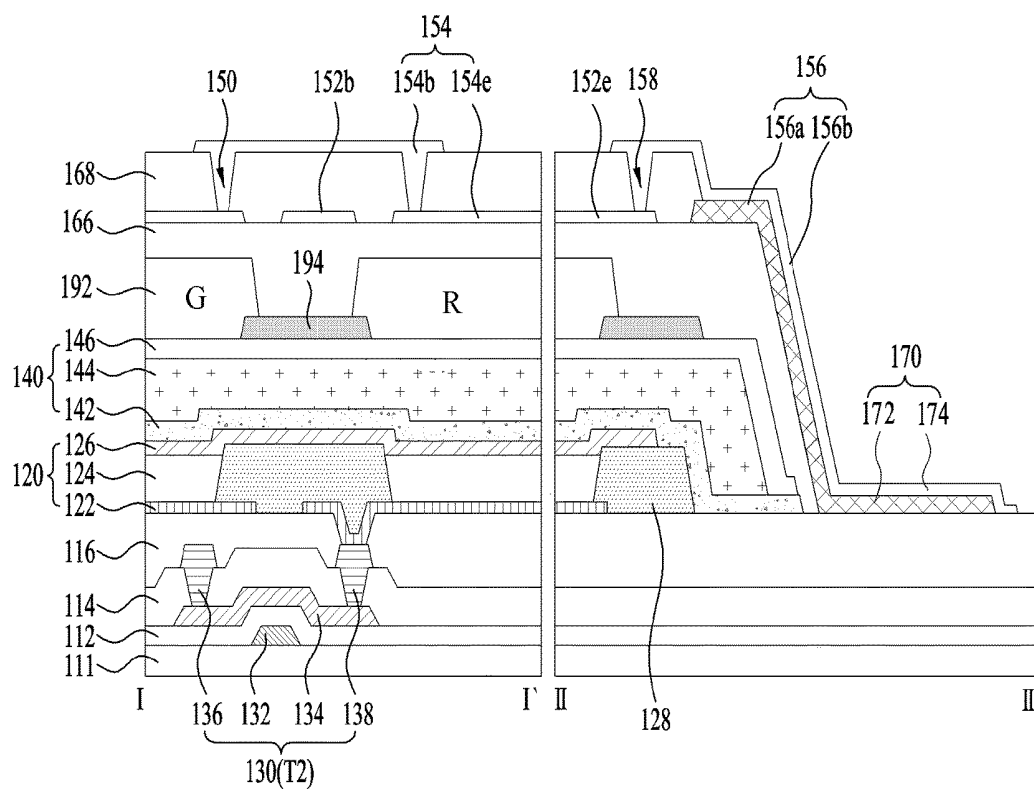
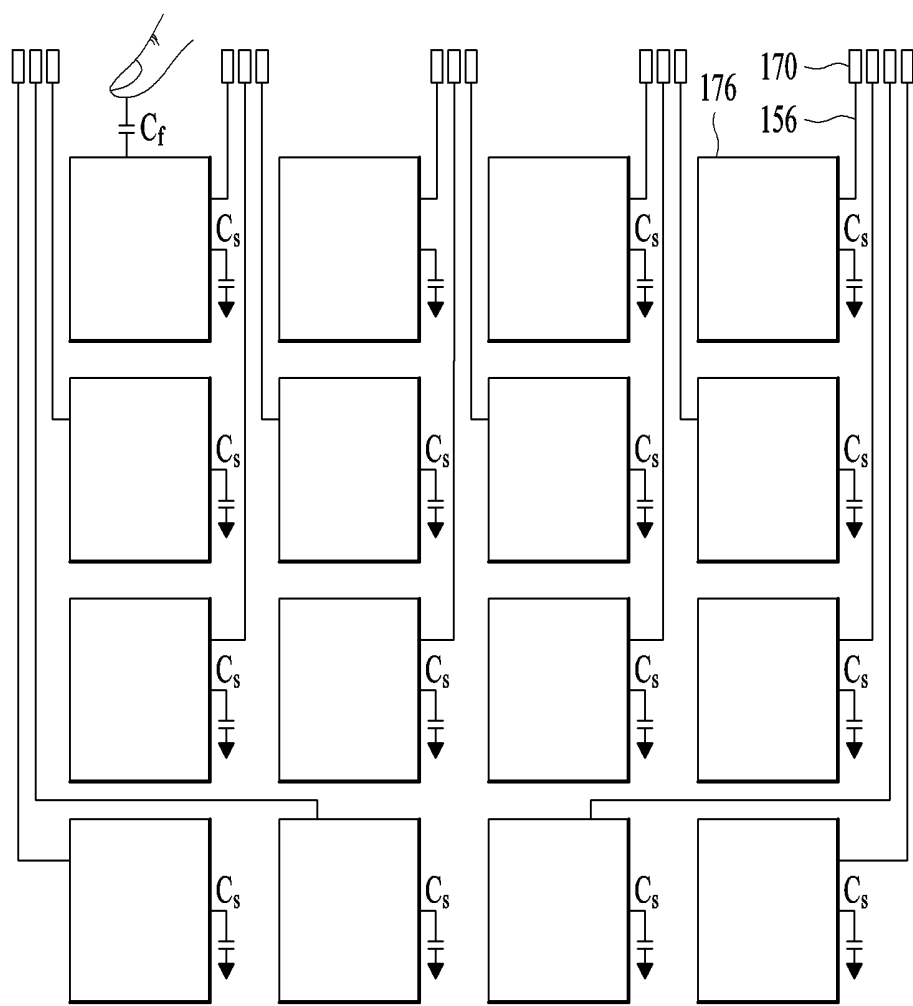


FIG.11



DISPLAY DEVICE WITH AN INTEGRATED TOUCH SENSOR

[0001] This application claims the benefit of Korean Patent Application No. 10-2016-0172664, filed on Dec. 16, 2016, which is hereby incorporated by reference as if fully set forth herein.

BACKGROUND

Technical Field

[0002] The present disclosure relates to a display device and a method of manufacturing the same, and more particularly, to a display device with an integrated touch sensor formed on an encapsulation stack of the display device.

Description of the Related Art

[0003] A touchscreen is an input device that allows a user to input a command by selecting one of multiple instructions displayed on a screen, such as a display device, using a user's hand or an object. That is, the touchscreen converts a contact position at which the user's hand or the object directly contacts the touchscreen into an electrical signal to receive the instruction selected at the contact position as an input signal. The touchscreen has come to be increasingly used, since the touchscreen is capable of replacing an additional input device that is connected to the display device for operation, such as a keyboard or a mouse.

[0004] The touchscreen is attached to the front of a display panel, such as a liquid crystal display panel or an organic electro-luminescent display panel, using an adhesive. Separately manufacturing and then attaching the touchscreen to the front of the display panel using adhesive is complicated and costly.

BRIEF SUMMARY

[0005] The present disclosure is directed to a display device and a method of manufacturing the same that allows for a touch sensor to be formed on a display device that would otherwise be prohibitively sensitive to environmental conditions associated with manufacturing a touch display. For instance, the stack of layers for a touch sensor can be applied and etched using lower temperature processes than are known in the art. The reduction in damaging environmental conditions can be provided by the specific structures protecting the underlying layers due to their position and dimensions, as well as by the specific material properties for the various selected layers.

[0006] Some embodiments provide a display device manufactured through a simplified process at reduced costs and a method of manufacturing the same.

[0007] Additional advantages, objects, and features of the embodiments will be set forth in part in the description which follows and in part will become apparent to those having ordinary skill in the art upon examination of the following or may be learned from practice of the various embodiments. The objectives and other advantages of the various embodiments may be realized and attained by the structure particularly pointed out in the written description and claims hereof as well as the appended drawings.

[0008] Some embodiments include an organic light-emitting display device having a touch sensor includes a plurality of touch electrodes on an encapsulation stack so as to cover a light-emitting element, wherein the touch electrodes are

deposited at a low temperature (between room temperature and 100° C.) and are crystallized through an annealing process, whereby it is possible to prevent damage to an organic light-emitting layer at the time of forming the touch electrodes. The touch electrodes are disposed on the encapsulation stack, with the result that an additional bonding process is not required, whereby the process is simplified and costs are reduced.

[0009] It is to be understood that both the foregoing general description and the following detailed description of the various embodiments are exemplary and explanatory and are intended to provide further explanation of the embodiments as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] The accompanying drawings are incorporated in and constitute a part of this application, illustrate the various embodiments of the disclosure, and, together with the description, serve to explain the various embodiments. In the drawings:

[0011] FIG. 1 is an isometric view showing an organic light-emitting display device having a touch sensor according to a first embodiment;

[0012] FIG. 2 is a plan view of an organic light-emitting display device having a touch sensor according to one embodiment;

[0013] FIG. 3 is a sectional view of an organic light-emitting display device having the touch sensor according to one embodiment;

[0014] FIG. 4A is a plan view showing another embodiment of the bridge shown in FIG. 3;

[0015] FIG. 4B is a sectional view showing the bridge of FIG. 4A taken at sectional line AA';

[0016] FIG. 5 is a sectional view showing another embodiment of a touch dielectric film shown in FIG. 3;

[0017] FIGS. 6A to 6D are sectional views illustrating a method of manufacturing the organic light-emitting display device shown in FIG. 3;

[0018] FIG. 7 is a sectional view showing an organic light-emitting display device having a touch sensor according to a second embodiment;

[0019] FIG. 8 is a detailed plan view of a touch electrode shown in FIG. 7;

[0020] FIGS. 9A to 9E are sectional views illustrating various steps of a method of manufacturing the organic light-emitting display device shown in FIG. 7;

[0021] FIG. 10 is a sectional view showing an organic light-emitting display device having a touch sensor according to a third embodiment, wherein the organic light-emitting display device includes a color filter; and

[0022] FIG. 11 is a plan view showing an organic light-emitting display device having a self-capacitance type touch sensor according to one embodiment.

DETAILED DESCRIPTION

[0023] Reference will now be made in detail to embodiments of the present disclosure, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers will be used throughout the drawings to refer to the same or like parts. In the following description, certain specific details are set forth in order to provide a thorough understanding of various embodiments of the disclosure. However, one skilled in the

art will understand that the disclosure may be practiced without these specific details. In other instances, well-known structures associated with electronic components and fabrication techniques have not been described in detail to avoid unnecessarily obscuring the descriptions of the embodiments of the present disclosure.

[0024] Unless the context requires otherwise, throughout the specification and claims that follow, the word “comprise” and variations thereof, such as “comprises” and “comprising,” are to be construed in an open, inclusive sense; that is, as “including, but not limited to.”

[0025] Reference throughout this specification to “one embodiment” or “an embodiment” means that a particular feature, structure or characteristic described in connection with the embodiment is included in at least one embodiment. Thus, the appearances of the phrases “in one embodiment” or “in an embodiment” in various places throughout this specification are not necessarily all referring to the same embodiment. Furthermore, the particular features, structures, or characteristics may be combined in any suitable manner in one or more embodiments.

[0026] As used in this specification and the appended claims, the singular forms “a,” “an,” and “the” include plural referents unless the content clearly dictates otherwise. It should also be noted that the term “or” is generally employed in its sense including “and/or” unless the content clearly dictates otherwise.

[0027] As used in the specification and the appended claims, the use of “correspond,” “corresponds,” and “corresponding” is intended to describe a ratio of or a similarity between referenced objects. The use of “correspond” or one of its forms should not be construed to mean the exact shape or size.

[0028] The present disclosure is directed to a touch sensor formed on a display device. The display device includes a light-emitting element that is integrally formed with a touch sensor. The display device includes various protective layers between the light-emitting element and the touch sensor, with the touch sensor having routing lines that route the touch sensor signals to base layers of the display device around the protective layers.

[0029] FIG. 1 is an isometric view showing an organic light-emitting display device 100 having a touch sensor 102 according to one embodiment.

[0030] The organic light-emitting display device 100 having the touch sensor 102 shown in FIG. 1 detects variation in capacitance of the mutual capacitor C_m (the touch sensor 102) due to a user's touch through touch electrodes, such as touch electrodes 152e and 154e shown in FIG. 2, during a touch period to sense whether a touch has been performed and the touched position. The organic light-emitting display device 100 having the touch sensor 102 shown in FIG. 1A displays an image through respective stack pixels each including a light-emitting element. Each stack pixel includes red (R), green (G), and blue (B) sub-pixels PXL. Alternatively, each stack pixel may include red (R), green (G), blue (B), and white (W) sub-pixels PXL. Other color combinations are also possible.

[0031] To this end, the organic light-emitting display device 100 shown in FIG. 1 includes a plurality of sub-pixels PXL arranged on a substrate 111 in a matrix fashion, an encapsulation stack 140 on the sub-pixels PXL, and mutual capacitor C_m on the encapsulation stack 140. The substrate 111 can be any one of many different substrates. In one

embodiment, the substrate is a flexible substrate. In another embodiment, the substrate is a rigid substrate.

[0032] As depicted in FIG. 1B, each of the sub-pixels PXL includes a pixel-driving circuit 119 and a light-emitting element 120 connected to the pixel-driving circuit 119. The pixel-driving circuit 119 includes a switching transistor T1, a driving transistor T2, and a storage capacitor Cst.

[0033] A scan pulse is supplied to a scan line SL connected to a terminal of the switching transistor T1. The switching transistor T1 is turned on by a data signal provided over a data line DL to transmit a control signal to the storage capacitor Cst and a gate electrode of the driving transistor T2.

[0034] In response to the control signal supplied to the gate electrode of the driving transistor T2, the driving transistor T2 controls current I supplied from a high-voltage (VDD) supply line to the light-emitting element 120 to adjust the amount of light emitted by the light-emitting element 120. Even when the switching transistor T1 is turned off, the driving transistor T2 supplies uniform current I to the light-emitting element 120 using the voltage charged in the storage capacitor Cst such that the light-emitting element 120 keeps emitting light until a control signal of the next frame is supplied.

[0035] As shown in FIG. 3, the driving thin film transistor T2 (130) includes a gate electrode 132, a semiconductor layer 134 overlapping the gate electrode 132, with a gate dielectric film 112 between the gate electrode 132 and the semiconductor layer 134. The gate dielectric film 112 is a first dielectric film. The driving thin film transistor T2 (130) also includes source and drain electrodes 136 and 138 formed through an interlayer dielectric film 114 on the semiconductor layer 134. The interlayer dielectric film 114 is a second dielectric film, so as to contact the semiconductor layer 134. The semiconductor layer 134 is formed of at least one material selected from among an amorphous semiconductor material, a polycrystalline semiconductor material, and an oxide semiconductor material.

[0036] The light-emitting element 120 includes an anode electrode 122, at least one light-emitting stack 124 formed on the anode electrode 122, and a cathode electrode 126 formed on the light-emitting stack 124.

[0037] The anode electrode 122 is electrically connected to the drain electrode 138 of the driving thin film transistor 130, exposed through a pixel contact hole formed through a passivation film 116, which is a third dielectric film.

[0038] The light-emitting stack 124 is formed on the anode electrode 122 in a light-emitting area defined by a bank 128. The light-emitting stack 124 can be formed by stacking a hole-related layer, an organic light-emitting layer, and an electron-related layer on the anode electrode 122 in that order or in the reverse order. In an alternate embodiment, the light-emitting stack 124 includes first and second light-emitting stacks opposite each other with a charge generation layer formed therebetween. In this embodiment, the organic light-emitting layer of one of the first and second light-emitting stacks generates blue light, and the organic light-emitting layer of the other of the first and second light-emitting stacks generates yellowish-green light. Consequently, white light is generated by combining the light from the first and second light-emitting stacks. The white light generated by the light-emitting stack 124 may be projected through a color filter (not shown), which is located above or under the light-emitting stack 124, to realize a color

image. In addition, each light-emitting stack **124** may generate colored light corresponding to each sub-pixel without an additional color filter to realize a color image. That is, the light-emitting stack **124** of the red (R) sub-pixel may generate red light, the light-emitting stack **124** of the green (G) sub-pixel may generate green light, and the light-emitting stack **124** of the blue (B) sub-pixel may generate blue light.

[0039] The cathode electrode **126** is formed so as to be on an opposite side of the light-emitting stack than the anode electrode **122**, with the cathode electrode connected to a low-voltage (VSS) supply line.

[0040] The encapsulation stack **140** prevents external moisture or oxygen from permeating into the light-emitting element **120**, which has low resistance to degradation in the presence of moisture or oxygen. One embodiment of the encapsulation stack **140** includes first and second inorganic encapsulation layers **142** and **146** and an organic encapsulation layer **144** formed between the first and second inorganic encapsulation layers **142** and **146**. The second inorganic encapsulation layer **146** is the uppermost layer. The encapsulation stack **140** includes at least two inorganic encapsulation layers **142** and **146** and at least one organic encapsulation layer **144**. In the present disclosure, an encapsulation stack **140** having a structure in which an organic encapsulation layer **144** is disposed between first and second inorganic encapsulation layers **142** and **146** will be described by way of example.

[0041] The first inorganic encapsulation layer **142** is formed on the substrate **111**, on which the cathode electrode **125** is formed, so as to be closest to the light-emitting element **120**. The first inorganic encapsulation layer **142** is formed of an inorganic dielectric material that can be deposited at a low temperature, such as silicon nitride (SiN_x), silicon oxide (SiO_x), silicon oxide nitride (SiON), or aluminum oxide (Al_2O_3). Consequently, the first inorganic encapsulation layer **142** is deposited in a low-temperature environment to reduce the risk of damage to the light-emitting stack **124**, which is susceptible to damage in a high-temperature environment.

[0042] The organic encapsulation layer **144** reduces stress between the layers due to bending of the organic light-emitting device and improves planarization. The organic encapsulation layer **144** is formed of an organic dielectric material, such as acrylic resin, epoxy resin, polyimide, polyethylene, or silicon oxycarbide (SiOC).

[0043] The second inorganic encapsulation layer **146** is formed on the substrate **111**, on which the organic encapsulation layer **144** is formed, so as to cover the upper surfaces and the side surfaces of the organic encapsulation layer **144** and the first inorganic encapsulation layer **142**. Consequently, the second inorganic encapsulation layer **146** minimizes or prevents external moisture or oxygen from permeating into the first inorganic encapsulation layer **142** and the organic encapsulation layer **144**. The second inorganic encapsulation layer **146** is formed of an inorganic dielectric material, such as silicon nitride (SiN_x), silicon oxide (SiO_x), silicon oxide nitride (SiON), or aluminum oxide (Al_2O_3).

[0044] A touch buffer film **166** is disposed on the encapsulation stack **140**. The touch buffer film **166** is formed between a touch-sensing line **154** and the light-emitting element **120** and between a touch-driving line **152** and the light-emitting element **120**. The touch buffer film **166** has a thickness of 500 Å to 5 μm in some embodiments. In some

embodiments, the touch buffer film **166** is omitted and the touch driving lines **152**, **156** are on a top side of the encapsulation stack **140**. Additionally, the distance between the touch-sensing line **154** and the cathode electrode **126** and between the touch-driving line **152** and the cathode electrode **126** is at least 5 μm, in some embodiments. Consequently, it may be possible to reduce minimize the capacitance value of a parasitic capacitor formed between the touch-sensing line **154** and the cathode electrode **126** and between the touch-driving line **152** and the cathode electrode **126**, thereby preventing interaction due to coupling between the touch-sensing line **154** and the cathode electrode **126** and between the touch-driving line **152** and the cathode electrode **126**. Meanwhile, in the case in which the distance between the touch-sensing line **154** and the cathode electrode **126** and between the touch-driving line **152** and the cathode electrode **126** is less than 5 μm, the touch performance is reduced as the result of interaction due to coupling between the touch-sensing line **154** and the cathode electrode **126** and between the touch-driving line **152** and the cathode electrode **126**.

[0045] In addition, the touch buffer film **166** may prevent a liquid chemical (e.g. a developing solution or an etching solution), which is used to form the touch-sensing line **154** and the touch-driving line **152**, or external moisture from permeating into the light-emitting stack **124**. Consequently, the touch buffer film **166** may prevent damage to the light-emitting stack **124**, which is susceptible to damage from exposure to liquid chemicals or to moisture.

[0046] The touch buffer film **166** is formed of an organic dielectric material at a low temperature, such as 100° C. or lower, and has a low dielectric constant of 1 to 3 in order to prevent damage to the light-emitting stack **124**, which has low resistance to high temperatures. For example, the touch buffer film **166** may be formed of an acryl-based material, an epoxy-based material, or a siloxane-based material. The touch buffer film **166**, which is formed of an organic dielectric material and exhibits planarization characteristics, may prevent damage to the encapsulation layers **142**, **144**, and **146** in the encapsulation stack **140** and breakage of the touch-sensing line **154** and the touch-driving line **152**, which are formed on the touch buffer film **166**, due to bending of the organic light-emitting display device.

[0047] The touch-sensing line **154** and the touch-driving line **152** are formed on the touch buffer film **166** so as to overlap each other in the state in which the touch-sensing line **154** and the touch-driving line **152** are separated by a touch dielectric film **168** that is disposed therebetween. Mutual capacitance C_m is formed at the intersection where the touch-sensing line **154** and the touch-driving line **152** are overlap. Consequently, the mutual capacitor C_m is charged by a touch-driving pulse supplied to the touch-driving line **152** and the mutual capacitor C_m is discharged by the touch-sensing line **154**. A user's finger in proximity to the touch-driving line **152** and the touch-sensing line **154** changes the capacitance of mutual capacitor C_m , which affects the electrical response to being charged and discharged thereby serving as the touch sensor **102**.

[0048] The touch-driving line **152** includes a plurality of first touch electrodes **152e** and first bridges **152b** for electrically interconnecting the first touch electrodes **152e**. The first touch electrodes **152e** are spaced apart from each other on the touch buffer film **166** by a predetermined distance in a Y direction, which is a first direction. Each of the first

touch electrodes **152e** is electrically connected to an adjacent first touch electrode **152e** via a corresponding one of the first bridges **152b**.

[0049] The first bridges **152b** are disposed on the touch buffer film **166**, which is disposed in the same plane as the first touch electrodes **152e**, so as to be electrically connected to the first touch electrode **152e** without requiring the formation of additional contact holes.

[0050] The touch-sensing line **154** includes a plurality of second touch electrodes **154e** and second bridges **154b** for electrically interconnecting the second touch electrodes **154e**. The second touch electrodes **154e** are spaced apart from each other on the touch buffer film **166** by a predetermined distance in an X direction, which is a second direction. Each of the second touch electrodes **154e** is electrically connected to an adjacent second touch electrode **154e** via a corresponding one of the second bridges **154b**. The second bridges **154b** are formed on the touch dielectric film **168**, and are exposed through touch contact holes **150**, which are formed through the touch dielectric film **168**, so as to be electrically connected to the second touch electrodes **154e**. In the same manner as the first bridges **152b**, the second bridges **154b** are arranged so as to overlap the bank **128**. Consequently, it is possible to prevent the reduction of an aperture ratio due to the first and second bridges **152b** and **154b**.

[0051] Meanwhile, each of the second bridges **154b**, which are disposed in a plane different from the plane in which the touch electrodes **152e** and **154e** are disposed, may be provided with a plurality of slits **151**, as shown in FIG. 4. The area of each second bridge **154b** shown in FIG. 4, which has a plurality of slits **151**, may be smaller than the area of each second bridge **154b** shown in FIG. 2, which has no slits **151**. Consequently, it is possible to reduce the amount of external light that is reflected by the second bridges **154b**, thereby preventing the reduction of visibility. Each second bridge **154b** having the slits **151** is formed of a transparent conductive layer or an opaque conductive layer. In the case in which each second bridge **154b** is formed of an opaque conductive layer, the second bridges **154b** overlap the bank **128**, whereby it is possible to prevent the reduction of an aperture ratio.

[0052] Returning to FIG. 3, the touch-driving line **152** is connected to a touch-driving unit (not shown) via a first routing line **156** and a touch-driving pad **170**. In addition, the touch-sensing line **154** is connected to the touch-driving unit via a second routing line **186** and a touch-sensing pad **180**.

[0053] The first routing line **156** electrically connects the touch-driving pad **170** to the first touch electrodes **152e**, whereby a touch-driving pulse from the touch-driving pad **170** is transmitted to the touch-driving line **152**. The second routing line **186** electrically connects the touch-sensing pad **180** to the second touch electrode **154e**, whereby a touch signal from the touch-sensing line **154** is transmitted to the touch-sensing pad **180**.

[0054] The first and second routing lines **156** and **186** are disposed on the touch buffer film **166** so as to cover the top and side surfaces of the encapsulation stack **140** whereby the first and second routing lines **156** and **186** contact the side surface of the touch buffer film **166**. In addition, the first and second routing lines **156** and **186** may contact the side surface of the inorganic encapsulation layer **146** so as to cover the side surface of the encapsulation stack **140** without the touch buffer film **166**. Each of the first and second

routing lines **156** and **186** includes a first conductive layer **156a** and a second conductive layer **156b** stacked on the first conductive layer **156a**. The first conductive layer **156a** is formed of a metal exhibiting high conductivity, such as Al, Ti, Cu, or Mo, so as to have a single- or multi-layer structure. For example, the first conductive layer **156a** may be formed to have a three-layer stack structure, such as Ti/Al/Ti or Mo/Al/Mo. A transparent conductive layer exhibiting high corrosion resistance and acid resistance, such as ITO or IZO, is used as the second conductive layer **156b**.

[0055] In order to contact the dielectric films **112**, **114**, and **116**, disposed between the substrate **111** and the encapsulation unit **140**, the touch-driving pad **170** and the touch-sensing pad **180** are disposed on the dielectric film (e.g. the passivation film **116**). Each of the touch-driving pad **170** and the touch-sensing pad **180** includes a pad electrode **172** and a pad cover electrode **174** formed on the pad electrode **172** so as to at least partially cover the pad electrode **172**.

[0056] The pad electrode **172** extends from the first conductive layers **156a** of the first and second routing lines **156** and **186**. The pad cover electrode **174** extends from the second conductive layers **156b** of the first and second routing lines **156** and **186**. The pad cover electrode **174** is formed so as to be exposed by a touch passivation film (not shown). Consequently, the pad cover electrode **174** is connected to a signal transmission film, on which the touch-driving unit is mounted. The touch passivation film is formed so as to cover the touch-sensing line **154** and the touch-driving line **152**, and thus may prevent the touch-sensing line **154** and the touch-driving line **152** from being corroded by external moisture. The touch passivation film can be formed of an organic dielectric material, configured in the form of a circular polarizer, or formed of an epoxy or acrylic film.

[0057] The organic light-emitting display device having the touch sensor according to the present disclosure, the manufacturing process is conducted at a low temperature after the organic light-emitting element **120** is formed (about 100° C. or lower) in order to protect the light-emitting stack **124**, which is vulnerable to damage at high temperatures. The manufacturing process can be changed depending on the materials of a conductive thin film layer and a dielectric thin film layer, which are formed on the organic light-emitting element **120**, as is discussed below. Specifically, in the case in which at least one dielectric thin film layer is selected from among the organic encapsulation layer **144** of the encapsulation stack **140**, the touch dielectric film **168**, and the touch buffer film **166**, which are disposed on the organic light-emitting element **120**, is formed of a photoacryl-based, epoxy-based, Parylene-C, Parylene-N, Parylene-F, or siloxane-based organic film, the dielectric thin film layer is coated on the substrate **111** and is cured at a temperature of 100° C. or lower.

[0058] In some embodiments, when at least one dielectric thin film layer is selected from among the inorganic encapsulation layers **142** and **146** of the encapsulation stack **140**, the touch dielectric film **168**, and the touch buffer film **166**, which are disposed on the organic light-emitting element **120**, is formed of an inorganic film, such as SiN_x, SiON, or SiO₂, the dielectric thin film layer is deposited on the substrate at a low temperature and washed. This process may be repeated more than once, for example, when the dielectric thin film layer is imparted with a multi-layer structure.

[0059] As shown in FIG. 5, a touch dielectric film 168 is formed to have a three-layer structure including first to third touch dielectric films 168a, 168b, and 168c. When the inorganic dielectric thin film layer is formed through a low-temperature deposition process, particles can be formed in the inorganic dielectric thin film layer by non-reacting material generated due to low activation energy during deposition. When the particles are removed through washing, pores are formed in the portions of the inorganic dielectric thin film layer from which the particles have been removed. In order to prevent the permeation of moisture through the pores, the inorganic dielectric thin film layer is formed to have a multi-layer structure such that the pores in the inorganic dielectric thin film layer are covered by the uppermost dielectric thin film layer. When at least one dielectric thin film layer selected from among the encapsulation stack 140, the touch dielectric film 168, and the touch buffer film 166 is formed to have a multi-layer structure, the respective layers may be formed of the same material, or at least one of the layers may be formed of a material different from the material of the other layers.

[0060] In some embodiments, when at least one conductive thin film layer selected from among the first and second touch electrodes 152e and 154e, the first and second bridges 152b and 154b, the first and second routing lines 156 and 186, the touch-sensing pad 180, and the touch-driving pad 170, which are disposed on the organic light-emitting element 120, is formed of a metal material, the conductive thin film layer is formed through a room-temperature deposition process.

[0061] In some embodiments, when at least one conductive thin film layer selected from among the first and second touch electrodes 152e and 154e, the first and second bridges 152b and 154b, the first and second routing lines 156 and 186, the touch-sensing pad 180, and the touch-driving pad 170, which are disposed on the organic light-emitting element 120, is formed of a transparent conductive layer, the conductive thin film layer is deposited at room temperature through a deposition process. The deposition process, such as sputtering, may occur without a heat treatment process performed at a temperature of 100° C. or higher, and is crystallized through a laser annealing process. Since the conductive thin film layer is deposited through a low-temperature process, it is possible to prevent damage to the light-emitting stack 124, which is disposed under the conductive thin film layer. In addition, since the conductive thin film layer has a crystalline state, it is possible to reduce the resistance value of the conductive thin film layer and to improve the transmittance of the conductive thin film layer. For example, each of a touch-driving line 152 and a touch-sensing line 154 formed of a crystalline transparent conductive layer having a thickness of 100 Å to 1000 Å may have a resistance of about 40Ω/□ to 150Ω/□, which is low. Consequently, it is possible to maintain a rapid response speed. In addition, each of a touch-driving line 152 and a touch-sensing line 154 formed of a crystalline transparent conductive layer having a thickness of 100 Å to 1000 Å may have a high transmittance of about 80% to 90%.

[0062] As described above, in the organic light-emitting display device having the touch sensor, the respective thin film layers (e.g., the touch electrodes 152e and 154e, the touch buffer film 166, and the touch dielectric film 168), which are disposed on the organic light-emitting element 120, are formed through a low-temperature process to

reduce the risk of damage to the light-emitting stack 124, which is vulnerable to damage at high temperatures. Furthermore, in a conventional organic light-emitting display device, a touchscreen is generally attached to the conventional organic light-emitting display device using an adhesive. In contrast, in the organic light-emitting display device, the touch electrodes 152e and 154e are formed on the encapsulation stack 140, with the result that an additional bonding process is not required, whereby the process is simplified and costs are reduced.

[0063] FIGS. 6A to 6D are sectional views illustrating a method of manufacturing the organic light-emitting display device having the touch sensor shown in FIG. 3.

[0064] Referring to FIG. 6A, a touch buffer film 166, first conductive layers 156a of first and second routing lines 156 and 186, and pad electrodes 172 of a touch-driving pad 170 and a touch-sensing pad 180 are formed over a substrate 111, on which a switching transistor, a driving transistor 130, an organic light-emitting element 120, and an encapsulation stack 140 are formed.

[0065] Specifically, an organic dielectric material is on a substrate 111 and over a switching transistor, a driving transistor 130, an organic light-emitting element 120, and an encapsulation stack 140 are formed, using a metal mask and is cured at a curing temperature of 100° C. or lower to form a touch buffer film 166. Subsequently, a first conductive layer is may be deposited as a blanket layer on the touch buffer film 166 at room temperature through a deposition process using sputtering, for example, and the first conductive layer is patterned by photolithography and etching. The etching step forms the first conductive layers 156a of first and second routing lines 156 and 186 and pad electrodes 172 of a touch-driving pad 170 and a touch-sensing pad 180 are formed. Each first conductive layer 156a is formed of a metal exhibiting high corrosion resistance and acid resistance, such as Al, Ti, Cu, or Mo, so as to have a single- or multi-layer structure. For example, each first conductive layer 156a may be formed to have a three-layer stack structure, such as Ti/Al/Ti or Mo/Al/Mo.

[0066] Referring to FIG. 6B, first and second touch electrodes 152e and 154e, first bridges 152b, pad cover electrodes 174, and second conductive layers 156b of the first and second routing lines 156 and 186 are formed on the substrate 111, on which the first conductive layers 156a and the pad electrodes 172 are formed.

[0067] Specifically, second conductive layers 156b in an amorphous state, such as ITO or IZO, are deposited as a blanket deposition on the substrate 111, on which the first conductive layers 156a and the pad electrodes 172 are formed, using a deposition method at room temperature, such as sputtering. Subsequently, a laser mask 184 having transmission parts TP and shielding parts SP is aligned over the second conductive layers 156b in the amorphous state. The transmission parts TP in the laser mask 184 correspond to regions in which first and second touch electrodes 152e and 154e, first bridges 152b, pad cover electrodes 174, and first and second routing lines 156 and 186 are to be formed, and the shielding parts SP in the laser mask 184 correspond to the other regions.

[0068] Laser beams are radiated to the second conductive layers 156b in the amorphous state through the transmission parts TP in the laser mask 184. As the result of such laser annealing, the portions of the second conductive layers 156b corresponding to the transmission parts TP, through which

the laser beams are transmitted, are converted from the amorphous state to a crystalline state, and the portions of the second conductive layers **156b** corresponding to the shielding parts SP, through which the laser beams are not transmitted, remain in the amorphous state. Subsequently, the second conductive layers **156b** in the amorphous state are selectively removed through a wet etching process using an OZ acid solution. As a result, the second conductive layers **156b** in the crystalline state are not wet-etched and thus form first and second touch electrodes **152e** and **154e**, first bridges **152b**, and pad cover electrodes **174**.

[0069] Referring to FIG. 6C, a touch dielectric film **168** having therein touch contact holes **150** is formed over the substrate **111**, on which the first and second touch electrodes **152e** and **154e** and the first bridges **152b** are formed.

[0070] Specifically, a touch dielectric film **168** having a thickness of 500 Å to 5 μm is formed over the substrate **111**, on which the first and second touch electrodes **152e** and **154e** and the first bridges **152b** are formed, through a deposition or coating process. In the case in which an organic film is used to form a touch dielectric film **168**, the organic film is coated on the substrate and cured at a temperature of 100° C. or lower to form a touch dielectric film **168**. In the case in which an inorganic film is used to form a touch dielectric film **168**, a low-temperature chemical vapor deposition (CVD) process and a washing process can be performed repeatedly, at least twice or more, to form a touch dielectric film **168** having a multi-layer structure. Subsequently, the touch dielectric film **168** is patterned by photolithography and etching to form touch contact holes **150**.

[0071] Referring to FIG. 6D, second bridges **154b** are formed on the substrate **111**, on which the touch dielectric film **168** having therein the touch contact holes **150** is formed. Specifically, a third conductive layer is formed on the substrate **111**, on which the touch dielectric film **168** having therein the touch contact holes **150** is formed. In the case in which a metal, such as Al, Ti, Cu, or Mo, is used to form a third conductive layer, the third conductive layer is formed at room temperature using a deposition method, such as sputtering. Subsequently, the third conductive layer is patterned by photolithography and etching to form second bridges **154b**.

[0072] FIG. 7 is a sectional view showing an organic light-emitting display device having a touch sensor according to a second embodiment. The organic light-emitting display device shown in FIG. 7 includes many similar components as the organic light-emitting display device shown in FIG. 3 except that first and second touch electrodes **152e** and **154e** are formed so as to have a multi-layer structure. Consequently, a detailed description of the same components will be omitted.

[0073] The organic light-emitting display device of FIG. 7 includes a touch-driving line and a touch-sensing line coupled to first and second routing lines and a touch-driving pad and a touch-sensing pad, respectively. Each of the touch-driving pad and the touch-sensing pad includes a pad electrode and a pad cover electrode formed on the pad electrode so as to at least partially cover the pad electrode. Each of the first and second routing lines includes a first conductive layer and a second conductive layer stacked on the first conductive layer. The touch-driving line includes a plurality of first touch electrodes and first bridges for electrically interconnecting the first touch electrodes. The touch-

sensing line includes a plurality of second touch electrodes and second bridges for electrically interconnecting the second touch electrodes. The first and second touch electrodes are covered by a touch dielectric film with contact through holes for the second bridges to connect to the second touch electrodes.

[0074] Each of the first and second touch electrodes **152e** and **154e** shown in FIG. 7 is configured to have a structure in which first and second conductive layers **182a** and **182b** having the same line width and the same shape are sequentially stacked. Each of the first and second touch electrodes **152e** and **154e** having the structure in which the first and second conductive layers **182a** and **182b** are stacked is formed in a mesh shape, as shown in FIG. 8. The first conductive layer **182a** is formed of an opaque metal exhibiting high conductivity, such as Al, Ti, Cu, or Mo, so as to have a single- or multi-layer structure. For example, the first conductive layer **182a** may be formed to have a three-layer stack structure, such as Ti/Al/Ti or Mo/Al/Mo. A crystalline transparent conductive layer exhibiting high corrosion resistance and acid resistance, such as ITO or IZO, is used as the second conductive layer **182b**.

[0075] Since the first conductive layer **182a** has higher conductivity than the second conductive layer **182b**, the first and second touch electrodes **152e** and **154e** may be formed as low-resistance electrodes. Consequently, the resistance and capacitance of the first and second touch electrodes **152e** and **154e** are reduced, whereby an RC time constant is reduced and thus touch sensitivity is improved. In addition, the line width of the first and second touch electrodes **152e** and **154e**, which are formed in the mesh pattern, is very small, with the result that it is possible to prevent the reduction of an aperture ratio and transmittance due to the opaque first conductive layers **182a** included in the first and second touch electrodes **152e** and **154e**.

[0076] FIGS. 9A to 9E are sectional views illustrating various steps of a method of manufacturing the organic light-emitting display device shown in FIG. 7.

[0077] First, an organic dielectric material is coated over a substrate **111**, on which a switching transistor, a driving transistor **130**, an organic light-emitting element **120**, and an encapsulation stack **140** are formed, using a metal mask. The organic dielectric material is then cured at a curing temperature of 100° C. or lower to form a touch buffer film **166**, as shown in FIG. 9A. Subsequently, first and second conductive layers **182a** and **182b** are sequentially deposited on the touch buffer film **166** at room temperature through a deposition process, such as sputtering. The first conductive layer **182a** is formed of a metal exhibiting high conductivity, such as Al, Ti, Cu, or Mo, so as to have a single- or multi-layer structure. A transparent conductive layer in an amorphous state, such as ITO or IZO, is used as the second conductive layer **182b**. Subsequently, a laser mask **184** having transmission parts TP and shielding parts SP is disposed on aligned over the second conductive layer **182b** in the amorphous state, as shown in FIG. 9B. The transmission parts TP in the laser mask **184** correspond to regions in which first and second touch electrodes **152e** and **154e**, first bridges **152b**, first and second routing lines **156** and **186**, a touch-sensing pad **180**, and a touch-driving pad **170** are to be formed, and the shielding parts SP in the laser mask **184** correspond to the other regions. Laser beams are radiated to the second conductive layer **182b** in the amorphous state through the transmission parts TP in the laser mask **184**.

[0078] As the result of such laser annealing, the portions of the second conductive layer **156b** corresponding to the transmission parts TP, through which the laser beams are transmitted, are converted from the amorphous state to a crystalline state, and the portions of the second conductive layer **182b** corresponding to the shielding parts SP, through which the laser beams are not transmitted, remain in the amorphous state. Subsequently, the second conductive layer **182b** in the amorphous state is selectively removed through a wet etching process using an OZ acid solution, as shown in FIG. 9C, and the second conductive layer **182b** in the crystalline state are not wet-etched. Subsequently, the first conductive layer **182a** is etched through a wet etching process using the second conductive layer **182b** in the crystalline state as a mask to form first and second touch electrodes **152e** and **154e**, first bridges **152b**, first and second routing lines **156** and **186**, a touch-sensing pad **180**, and a touch-driving pad **170**, as shown in FIG. 9D. Subsequently, as shown in FIG. 9E, a touch dielectric film **168** having a thickness of 500 Å to 5 μm is formed over the substrate **111** through a deposition or coating process, and the touch dielectric film **168** is patterned by photolithography and etching to form touch contact holes **150**. Subsequently, a third conductive layer is deposited on the touch dielectric film **168** having therein the touch contact holes **150** at room temperature using a deposition method, such as sputtering, and is then patterned by photolithography and etching to form second bridges **154b**.

[0079] FIG. 10 is a sectional view showing an organic light-emitting display device according to a third embodiment of the present disclosure. The organic light-emitting display device shown in FIG. 10 includes many similar components as the organic light-emitting display device shown in FIG. 3. However, the organic light-emitting display device shown in FIG. 10 further includes a color filter **192** disposed on an encapsulation stack **140** or a touch buffer film **166** so as to be located between the encapsulation stack **140** and touch electrodes **152e** and **154e**. Consequently, a detailed description of the same components will be omitted.

[0080] The organic light-emitting display device includes a buffer layer between the encapsulation stack and the touch-driving line **152** and the touch-sensing line **154**, and a the touch dielectric film on the first and second touch electrodes **152e** and **154e**, with additional contact through holes **158** which are filled by a second conductive layer.

[0081] The color filter **192** is formed between a touch-sensing line **154** and a light-emitting element **120** and between a touch-driving line **152** and the light-emitting element **120**, together with the touch buffer film **166**. The distance between the touch-sensing line **154** and the light-emitting element **120** and between the touch-driving line **152** and the light-emitting element **120** is increased by the color filter **192** and the touch buffer film **166**. Consequently, it is possible to minimize the capacitance value of a parasitic capacitor formed between the touch-sensing line **154** and the light-emitting element **120** and between the touch-driving line **152** and the light-emitting element **120**, thereby reducing interaction due to coupling between the touch-sensing line **154** and the light-emitting element **120** and between the touch-driving line **152** and the light-emitting element **120**. In addition, the touch buffer film **166** and the color filter **192** may prevent a liquid chemical (e.g., a developing solution or an etching solution), which is used to form the touch-sensing line **154** and the touch-driving line **152**, which is disposed on

the touch buffer film **166**, or external moisture from permeating into the light-emitting stack **124**. Consequently, the touch buffer film **166** and the color filter **192** may reduce the risk of damage to the light-emitting stack **124**, which degrades in the presence of liquid chemicals or moisture. As shown in FIG. 10, the touch electrodes have been described as being disposed on the color filter **192** by way of example. Alternatively, the color filter **192** may be disposed on the touch electrodes. In this case, the touch electrodes **152e** and **154e** are disposed between the color filter **192** and the encapsulation stack **140**.

[0082] A black matrix **194** is disposed between color filters **192**. The black matrix serves to divide sub-pixel areas from each other and to prevent optical interference between adjacent sub-pixels and screen bleed. The black matrix **194** may be formed of a high-resistance black dielectric material, or may be formed by stacking at least two of red (R), green (G), and blue (B) color filters **192**.

[0083] As described above with respect to some of the various embodiments, the respective thin film layers (e.g. the touch electrodes, the touch buffer film, and the touch dielectric film of the various embodiments), which are disposed on the organic light-emitting element **120**, are formed through a low-temperature process, thereby reducing the risk of damage to the light-emitting element **120**. Furthermore, in a conventional organic light-emitting display device, a touchscreen is generally attached to the organic light-emitting display device using an adhesive. In contrast, in the organic light-emitting display device according to the present disclosure, the touch electrodes **152e** and **154e** are disposed on the encapsulation unit **140**, with the result that an additional bonding process is not required, whereby the process is simplified and costs are reduced.

[0084] The bridges **154b** and the second touch electrodes **154e** of the touch-sensing line **154** have been described by way of example as being formed in different planes and being connected to each other via the touch contact holes **150**. Alternatively, the bridges **152b** and the first touch electrodes **152e** of the touch-driving line **152** may be disposed in different planes and may be connected to each other via the touch contact holes **150**. Furthermore, the mutual-capacitance type touch sensor formed between the touch-sensing line **154** and the touch-driving line **152**, which intersect each other, has been described by way of example. Alternatively, self-capacitance type touch sensors Cs shown in FIG. 11 may be used. A plurality of touch electrodes **176** shown in FIG. 11 has electrically independent self-capacitances. Consequently, the touch electrodes may be used as self-capacitance type touch sensors Cs for detecting variation in mutual capacitance due to a user's touch. In a self-capacitance sensing method using the touch electrodes **176**, when a driving signal supplied through the touch pad **170** is applied to the touch electrodes **176** via the routing line **156**, electric charges Q are accumulated in the touch sensors Cs. At this time, when a user's finger or a conductive object contacts one of the touch electrodes **176**, parasitic capacitance Cf is further applied to the self-capacitance type touch sensor Cs, whereby the capacitance value is changed. As a result, a difference in the capacitance value between the touch sensor Cs that the finger has contacted and the touch sensors Cs that the finger has not contacted is formed, whereby it is possible to determine whether the touch has been performed. The touch electrodes **176** shown in FIG. 11 are disposed on the encapsulation stack **140** or the touch

buffer film 166 so as to cover the light-emitting element 120, in the same manner as in the mutual-capacitance type touch electrodes 152e and 154e shown in FIG. 3. In this case, the touch electrodes 176 shown in FIG. 11 and the routing line 156 connected to the touch electrodes 176 may be formed through a deposition process conducted at a low temperature (between room temperature and 100° C.), a laser annealing process, or an etching process so as to exhibit crystalline characteristics. Consequently, it is possible to prevent damage to the light-emitting stack 124 at the time of forming the touch electrodes 176.

[0085] As can be appreciated from the above description, the touch electrodes are formed through a low-temperature deposition process onto the light emitting element, and the state of the touch electrodes is changed to a crystalline state through a laser annealing process. It is thus possible to form the touch electrodes so as to have low resistance and to reduce the risk of damage to the light-emitting stack. In addition, the touch electrodes may be formed through a laser annealing process and a wet etching process. Consequently, it is possible to reduce the number of processes and to minimize the amount of etching to be performed, compared to a conventional method of forming the touch electrodes by photolithography and etching. In particular, it is possible to form the touch electrodes without a photoresist coating process, a developing process, or a stripping process, whereby it is possible to minimize the number of processes and thus to reduce costs. Furthermore, in a conventional organic light-emitting display device, a touchscreen is generally attached to the conventional organic light-emitting display device using an adhesive. In contrast, the touch electrodes of the present disclosure can be formed directly on the encapsulation stack without an adhesive, and the touch pads can be formed on the dielectric film between the substrate and the encapsulation stack. As a result, an additional bonding process is not required, whereby the process is simplified and costs are reduced.

[0086] It will be apparent to those skilled in the art that various modifications and variations can be made in the embodiments without departing from the spirit or scope of the disclosure. Thus, it is intended that the present disclosure covers all modifications and variations of the embodiments, and their equivalents, that come within the scope of any part of the disclosure including the specification, the figures, and the appended claims.

[0087] In general, in the following claims, the terms used should not be construed to limit the claims to the specific embodiments disclosed in the specification and the claims, but should be construed to include all possible embodiments along with the full scope of equivalents to which such claims are entitled. Accordingly, the claims are not limited by the disclosure.

What is claimed is:

1. A display device, comprising:

a substrate;

a light-emitting element disposed on the substrate;

an encapsulation stack disposed on the light-emitting element;

at least one layer of dielectric film disposed between the substrate and the encapsulation stack;

a plurality of touch electrodes disposed on the encapsulation stack, at least one of the plurality of touch electrodes being formed of a crystalline transparent conductive layer; and

a touch pad electrically connected to a first one of the plurality of touch electrodes, the touch pad on the at least one layer of dielectric film.

2. The display device according to claim 1, further comprising a routing line electrically connected to the touch pad and to the touch electrodes, the routing line covering a side surface of the encapsulation stack.

3. The display device according to claim 2, wherein the routing line contacts the side surface of the encapsulation stack.

4. The display device according to claim 3, wherein the routing line includes a first layer and a second layer, the first layer being a metal and the second layer being formed of a crystalline transparent conductive layer.

5. The display device according to claim 1, wherein the touch pad includes a first layer and a second layer, the first layer being a metal and the second layer being formed of a crystalline transparent conductive layer.

6. The display device according to claim 5, wherein the first one of the plurality of touch electrodes is the same layer as the second layer of the touch pad.

7. The display device according to claim 1, further comprising:

a touch buffer film formed between the encapsulation stack and the touch electrodes, wherein

the touch buffer film is formed from at least one of a photoacryl-based, epoxy-based, Parylene-C, Parylene-N, Parylene-F, and siloxane-based organic film.

8. The display device according to claim 1, wherein the plurality of touch electrodes comprise:

a first plurality of touch electrodes arranged on the encapsulation stack in a first direction; and

a second plurality of touch electrodes arranged on the encapsulation stack in a second direction, the second direction orthogonal to the first direction.

9. The display device according to claim 8, wherein each of the first and second plurality of touch electrodes is formed of a crystalline transparent conductive layer.

10. The display device according to claim 8, wherein each one of the first and second plurality of touch electrodes includes a first layer and a second layer.

11. The display device according to claim 10, wherein each of the first layers of the first and second plurality of touch electrodes comprises a crystalline transparent conductive layer and each of the second layers of the first and second plurality of touch electrodes comprises an opaque conductive layer disposed under the crystalline transparent conductive layers of the first and second touch electrodes.

12. The display device according to claim 8, further comprising:

a touch dielectric film disposed between the first plurality of touch electrodes and the second plurality of touch electrodes;

a first bridge for interconnecting the first plurality of touch electrodes; and

a second bridge for interconnecting the second plurality of touch electrodes.

13. The display device according to claim 12, wherein the touch dielectric film is disposed between the first bridge and the second bridge.

14. The display device according to claim 13, wherein at least one of the first and second bridges has at least one slit.

15. The display device according to claim 12, wherein the encapsulation stack comprises:

- a first inorganic encapsulation layer disposed on the light-emitting element;
- a second inorganic encapsulation layer disposed on the light-emitting element; and
- an organic encapsulation layer disposed between the first and second inorganic encapsulation layers.

16. The display device according to claim 15, wherein at least one of the touch dielectric film and the organic encapsulation layer is formed from at least one of a photoacryl-based, epoxy-based, Parylene-C, Parylene-N, Parylene-F, and siloxane-based organic film.

17. The display device according to claim 15, wherein at least one of the touch dielectric film and the inorganic encapsulation layers is formed from an inorganic film having a multi-layer structure including SiN_x , SiON , or SiO_2 .

18. The display device according to claim 1, wherein each of the plurality of touch electrodes is formed in a mesh pattern.

19. The display device according to claim 1, wherein each of the plurality of touch electrodes is configured to detect an electrically independent self-capacitance.

20. The display device according to claim 1, further comprising a color filter disposed between the encapsulation stack and the plurality of touch electrodes.

21. The display device according to claim 1, further comprising:

- a color filter disposed on the plurality of touch electrodes, the plurality of touch electrodes being between the color filter and the encapsulation stack.

22. The display device according to claim 1, further comprising:

- a transistor connected to the light-emitting element;
- a first dielectric film disposed between a gate electrode and an active layer of the transistor;
- a second dielectric film disposed between the active layer and source and drain electrodes; and
- a third dielectric film disposed between the source and drain electrodes and the light-emitting element, wherein the at least one layer of dielectric film is at least one of the first, second, and third dielectric films.

23. A method of manufacturing a display device, comprising:

- forming at least one layer of dielectric film on a substrate
- forming a light-emitting element on the at least one layer of dielectric film;

forming an encapsulation stack on the light-emitting element;

forming a plurality of touch electrodes, each including a crystalline transparent conductive layer; and

forming a touch pad on the encapsulation stack, the forming a touch pad including:

- electrically connecting the touch pad to one of the plurality of touch electrodes; and
- contacting the at least one layer of dielectric film disposed between the substrate and the encapsulation stack with the touch pad.

24. The method of manufacturing a display device according to claim 23, wherein the forming the plurality of touch electrodes comprises:

depositing an amorphous transparent conductive layer on the encapsulation stack at room temperature, the amorphous transparent conductive layer having a first portion and a second portion;

crystallizing the first portion of the amorphous transparent conductive layer into a plurality of crystalline touch electrodes;

removing the second portion of the amorphous transparent conductive layer; and

forming a touch dielectric film on the plurality of crystalline touch electrodes.

25. The method of manufacturing a display device according to claim 24, further comprising:

forming a routing line, the forming the routing line including forming a first layer of metal and a second layer of an amorphous transparent conductive material, and crystallizing the second layer of the routing line.

26. The method of manufacturing a display device according to claim 25, wherein forming the touch pad includes forming a first layer of metal and a second layer of an amorphous transparent conductive material, and crystallizing the second layer of the touch pad, wherein the crystallizing the first portion of the amorphous transparent conductive layer, the crystallizing the second layer of the routing line, and the crystallizing the second layer of the touch pad are the same step.

27. The method of manufacturing a display device according to claim 24, wherein forming the touch pad includes forming a first layer of metal and a second layer of an amorphous transparent conductive material, wherein the crystallizing the first portion of the amorphous layer includes crystallizing the second layer of the touch pad.

* * * * *

专利名称(译)	具有集成触摸传感器的显示设备		
公开(公告)号	US20180175116A1	公开(公告)日	2018-06-21
申请号	US15/712711	申请日	2017-09-22
[标]申请(专利权)人(译)	乐金显示有限公司		
申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
当前申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
[标]发明人	SONG TAE JOON LEE KYU HWANG		
发明人	SONG, TAE-JOON LEE, KYU-HWANG		
IPC分类号	H01L27/32 G06F3/041 H01L51/56 H01L51/52		
CPC分类号	H01L27/323 G06F3/0412 H01L51/56 H01L51/5203 G06F2203/04103 H01L27/3211 H01L51/5237 G06F3/0443 G06F3/0446 G06F3/044		
优先权	1020160172664 2016-12-16 KR		
其他公开文献	US10658434		
外部链接	Espacenet USPTO		

摘要(译)

公开了一种有机发光显示装置及其制造方法。有机发光显示装置包括在覆盖发光元件的封装叠层上具有多个触摸电极的触摸传感器。触摸电极在低温下形成并通过退火工艺结晶，由此可以防止在形成触摸电极时损坏有机发光层。因此，可以在封装叠层上形成触摸电极而无需额外的键合工艺来将触摸传感器键合到有机发光显示装置。

